



## SILICON 2.0 Watt ZENER DIODES

### DESCRIPTION

The SMBJ5913B - SMBJ5956B series of surface mount 2.0 watt Zeners provides a selection from 3.3 to 200 volts with different tolerance options available. This series is equivalent to the JEDEC registered 1N5913 thru 1N5956 series with identical electrical characteristics except these are rated at 2.0 W instead of 1.5 W with the lower thermal resistance features of the surface mount packaging. Its featured J-bend design in the DO-214AA package is ideal for greater PC board mounting density. It is also available as RoHS compliant with an e3 suffix. Microsemi also offers numerous other Zener products to meet higher and lower power applications.

**Important:** For the latest information, visit our website <http://www.microsemi.com>.

### FEATURES

- Surface mount equivalent to JEDEC registered 1N5913 thru 1N5956.
- Ideal for high-density and low-profile mounting.
- Zener voltage available 3.3 V to 200 V.
- Standard voltage tolerances are plus/minus 5% and 10%.
- A tighter tolerance is available in plus or minus 2%.
- RoHS compliant versions available.



**DO-214AA**

**J-bend Package**

NOTE: All SMB series are equivalent to prior SMS package identifications.

Also available in:

**DO-215AA package**

(Gull-wing surface mount)



[SMBG5913 – SMBG5956B](#)

### APPLICATIONS / BENEFITS

- Regulates voltage over a broad operating current and temperature range.
- Wide selection from 3.3 to 200 V.
- Non-sensitive to ESD per MIL-STD-750 method 1020.
- Withstands high surge stresses (see [Figure 2](#)).
- Minimal changes of voltage versus current.
- High specified maximum current ( $I_{ZM}$ ) when adequately heat sunk.
- Moisture classification is Level 1 per IPC/JEDEC J-STD-020B with no dry pack required.

### MAXIMUM RATINGS

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	$T_J$ and $T_{STG}$	-65 to +150	°C
Thermal Resistance Junction-to-Lead	$R_{\Theta JL}$	35	°C/W
Thermal Resistance Junction-to-Ambient <sup>(1)</sup>	$R_{\Theta JA}$	100	°C/W
Steady-State Power Dissipation @ $TL \leq 80$ °C <sup>(2)</sup>	$P_D$	2.0	W
Forward Voltage @ 200 mA	$V_F$	1.2	V
Solder Temperature @ 10 s	$T_{SP}$	260	°C

- Notes:**
1. When mounted on FR4 PC board (1oz Cu) with recommended footprint (see [last page](#)).
  2. Or 1.25 watts at  $T_A = 25$  °C when mounted on FR4 PC board with recommended footprint (also see [Figure 1](#).)

**MSC – Lawrence**

6 Lake Street,  
Lawrence, MA 01841  
Tel: 1-800-446-1158 or  
(978) 620-2600  
Fax: (978) 689-0803

**MSC – Ireland**

Gort Road Business Park,  
Ennis, Co. Clare, Ireland  
Tel: +353 (0) 65 6840044  
Fax: +353 (0) 65 6822298

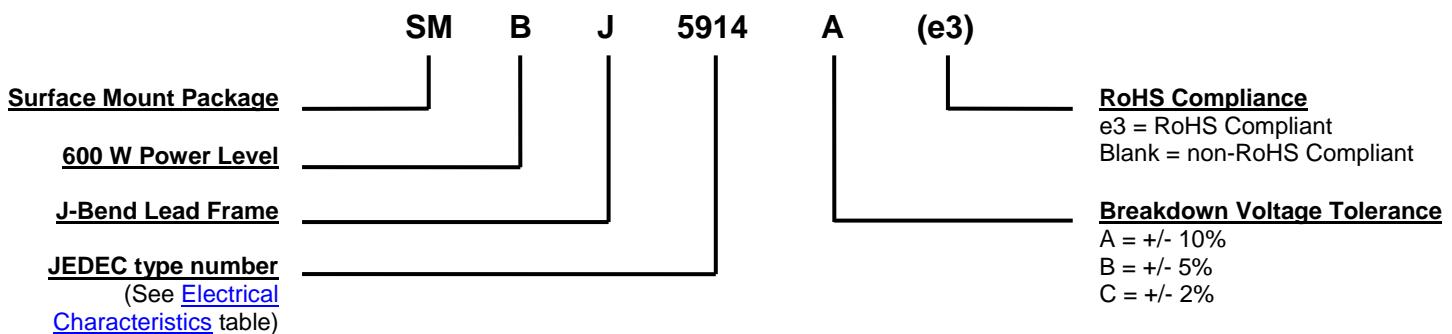
**Website:**

[www.microsemi.com](http://www.microsemi.com)

### MECHANICAL and PACKAGING

- CASE: Void-free transfer molded thermosetting epoxy body meeting UL94V-0.
- TERMINALS: Tin-lead or RoHS compliant annealed matte-tin plating solderable per MIL-STD-750, method 2026.
- MARKING: Part number without SMBx prefix (e.g. 5914B, 5914Be3, MX5946C, 5956D, etc.).
- POLARITY: Cathode indicated by band. Diode to be operated with the banded end positive with respect to the opposite end for Zener regulation.
- TAPE & REEL option: Standard per EIA-481-1-A with 12 mm tape (add "TR" suffix to part number). Consult factory for quantities.
- WEIGHT: 0.1 grams
- See [Package Dimensions](#) on last page.

### PART NOMENCLATURE



### SYMBOLS & DEFINITIONS

Symbol	Definition
$I_R$	Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.
$I_z$ , $I_{zT}$ , $I_{zk}$	Regulator Current: The dc regulator current ( $I_z$ ), at a specified test point ( $I_{zT}$ ), near breakdown knee ( $I_{zk}$ ).
$I_{zM}$	Maximum Regulator (Zener) Current: The maximum rated dc current for the specified power rating.
$V_R$	Reverse Voltage: The reverse voltage dc value, no alternating component.
$V_z$	Zener Voltage: The Zener voltage the device will exhibit at a specified current ( $I_z$ ) in its breakdown region.
$Z_{zT}$ or $Z_{zk}$	Dynamic Impedance: The small signal impedance of the diode when biased to operate in its breakdown region at a specified rms current modulation (typically 10% of $I_{zT}$ or $I_{zk}$ ) and superimposed on $I_{zT}$ or $I_{zk}$ respectively.

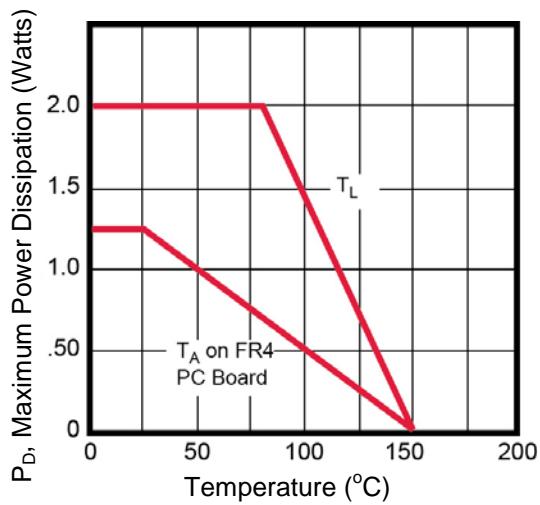
**ELECTRICAL CHARACTERISTICS**

MICROSEMI PART NUMBER	ZENER VOLTAGE $V_Z$	TEST CURRENT $I_{ZT}$	DYNAMIC IMPEDANCE $Z_{ZT}$	KNEE CURRENT $I_{ZK}$	KNEE IMPEDANCE $Z_{ZK}$	REVERSE CURRENT $I_R$	REVERSE VOLTAGE $V_R$	MAX. DC CURRENT $I_{ZM}$
	Volts	mA	Ohms	mA	Ohms	$\mu$ A	Volts	mA
SMBJ5913B	3.3	113.6	10.0	1.0	500	100.0	1.0	606
SMBJ5914B	3.6	104.2	9.0	1.0	500	75.0	1.0	554
SMBJ5915B	3.9	96.1	7.5	1.0	500	25.0	1.0	512
SMBJ5916B	4.3	87.2	6.0	1.0	500	10.0	1.0	464
SMBJ5917B	4.7	79.8	5.0	1.0	500	5.0	1.5	425
SMBJ5918B	5.1	73.5	4.0	1.0	400	5.0	2.0	392
SMBJ5919B	5.6	66.9	2.0	1.0	300	5.0	3.0	356
SMBJ5920B	6.2	60.5	2.0	1.0	200	5.0	4.0	321
SMBJ5921B	6.8	55.1	2.5	1.0	200	5.0	5.2	293
SMBJ5922B	7.5	50.0	3.0	0.5	400	5.0	6.0	266
SMBJ5923B	8.2	45.7	3.5	0.5	400	5.0	6.5	242
SMBJ5924B	9.1	41.2	4.0	0.5	500	5.0	7.0	218
SMBJ5925B	10	37.5	4.5	0.25	500	5.0	8.0	200
SMBJ5926B	11	34.1	5.5	0.25	550	1.0	8.4	181
SMBJ5927B	12	31.2	6.5	0.25	550	1.0	9.1	166
SMBJ5928B	13	28.8	7.0	0.25	550	1.0	9.9	153
SMBJ5929B	15	25.0	9.0	0.25	600	1.0	11.4	133
SMBJ5930B	16	23.4	10.0	0.25	600	1.0	12.2	122
SMBJ5931B	18	20.8	12.0	0.25	650	1.0	13.7	110
SMBJ5932B	20	18.7	14.0	0.25	650	1.0	15.2	100
SMBJ5933B	22	17.0	17.5	0.25	650	1.0	16.7	90
SMBJ5934B	24	15.6	19.0	0.25	700	1.0	18.2	82
SMBJ5935B	27	13.9	23.0	0.25	700	1.0	20.6	73
SMBJ5936B	30	12.5	28.0	0.25	750	1.0	22.8	66
SMBJ5937B	33	11.4	33.0	0.25	800	1.0	25.1	60
SMBJ5938B	36	10.4	38.0	0.25	850	1.0	27.4	54
SMBJ5939B	39	9.6	45.0	0.25	900	1.0	29.7	50
SMBJ5940B	43	8.7	53.0	0.25	950	1.0	32.7	45
SMBJ5941B	47	8.0	67.0	0.25	1000	1.0	35.8	41
SMBJ5942B	51	7.3	70.0	0.25	1100	1.0	38.8	38
SMBJ5943B	56	6.7	86.0	0.25	1300	1.0	42.6	34
SMBJ5944B	62	6.0	100.0	0.25	1500	1.0	47.1	32
SMBJ5945B	68	5.5	120.0	0.25	1700	1.0	51.2	29
SMBJ5946B	75	5.0	140.0	0.25	2000	1.0	56.0	26
SMBJ5947B	82	4.6	160.0	0.25	2500	1.0	62.2	24
SMBJ5948B	91	4.1	200.0	0.25	3000	1.0	69.2	10
SMBJ5949B	100	3.7	250.0	0.25	3100	1.0	76.0	20
SMBJ5950B	110	3.4	300.0	0.25	4000	1.0	83.6	17
SMBJ5951B	120	3.1	380.0	0.25	4500	1.0	91.2	16
SMBJ5952B	130	2.9	450.0	0.25	5000	1.0	98.8	14
SMBJ5953B	150	2.5	600.0	0.25	6000	1.0	114.0	13
SMBJ5954B	160	2.3	700.0	0.25	6500	1.0	121.6	12
SMBJ5955B	180	2.1	900.0	0.25	7000	1.0	136.8	10
SMBJ5956B	200	1.9	1200.0	0.25	8000	1.0	152.0	9

**NOTE 1:** Zener voltage ( $V_Z$ ) is measured at  $T_L = 30^\circ\text{C}$  and 20 seconds after application of dc current.

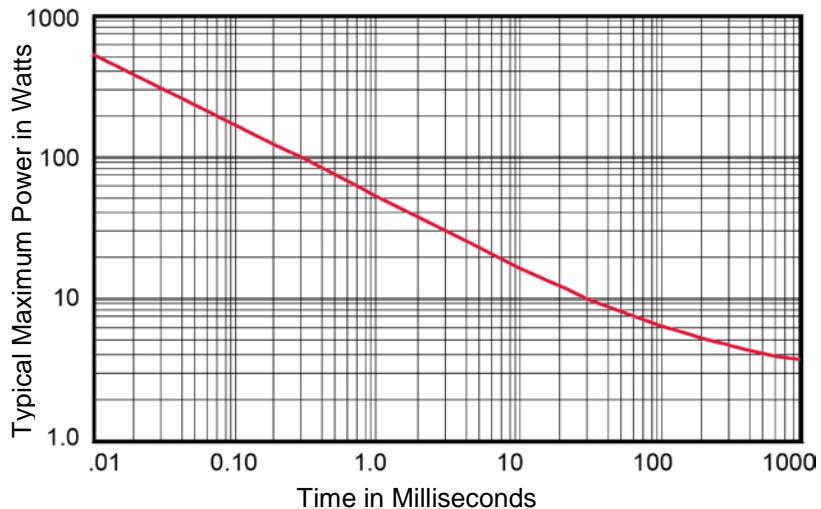
**NOTE 2:** The Zener impedance is derived from 1 kHz ac voltage resulting from an ac current modulation having an rms value equal to 10% of the dc Zener current ( $I_{ZT}$  or  $I_{ZK}$ ) superimposed on  $I_{ZT}$  or  $I_{ZK}$ . See [MicroNote 202](#) for Zener impedance variation with different operating currents.

**NOTE 3:** The maximum dc current ( $I_{ZM}$ ) is based only on the maximum power of 2.0 watts at  $T_L \leq 80^\circ\text{C}$ . These values must be reduced by 37.5% (1.25 W) when mounted on PC boards as described in [maximum ratings](#).

**GRAPHS**


$T_L$  Lead temp ( $^{\circ}\text{C}$ ), or  $T_A$  on FR4 PC Board

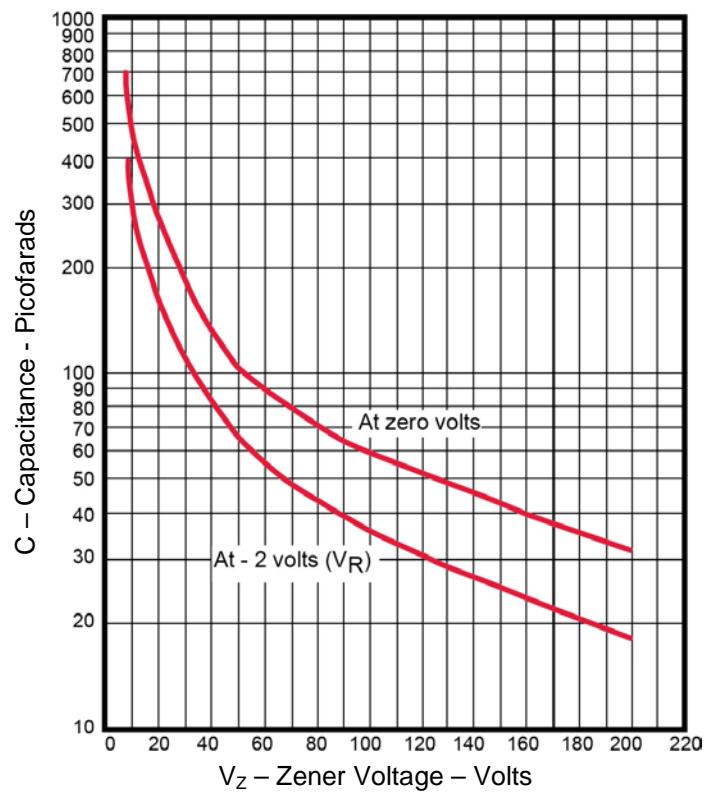
**FIGURE 1 – Power Derating Curve**



**FIGURE 2 – Transient Surge Capability**

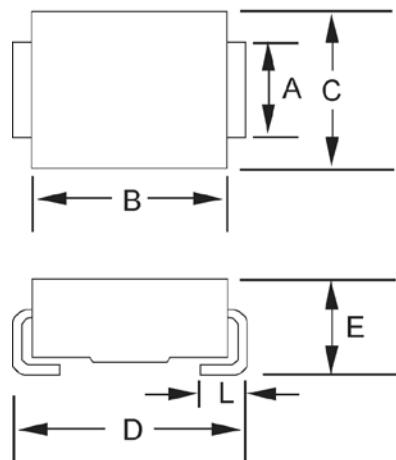
Square-Wave Pulse Width

(non-Repetitive) in Milliseconds



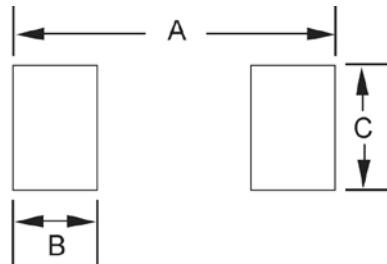
**FIGURE 3 – Capacitance vs Zener Voltage**

### PACKAGE DIMENSIONS



Ltr	Dimensions			
	Inch		Millimeters	
	Min	Max	Min	Max
A	.077	.083	1.96	2.10
B	.160	.180	4.06	4.57
C	.130	.155	3.30	3.94
D	.205	.220	5.21	5.59
E	.077	.104	1.95	2.65
L	.030	.060	.760	1.52

### PAD LAYOUT



	Inch	Millimeters
A	0.260	6.60
B	0.085	2.16
C	0.110	2.79